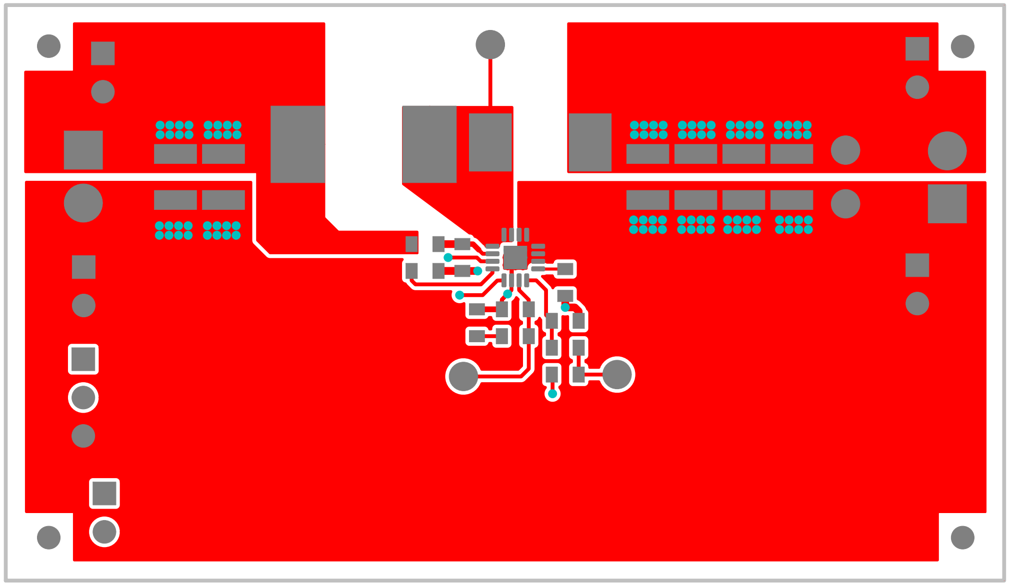
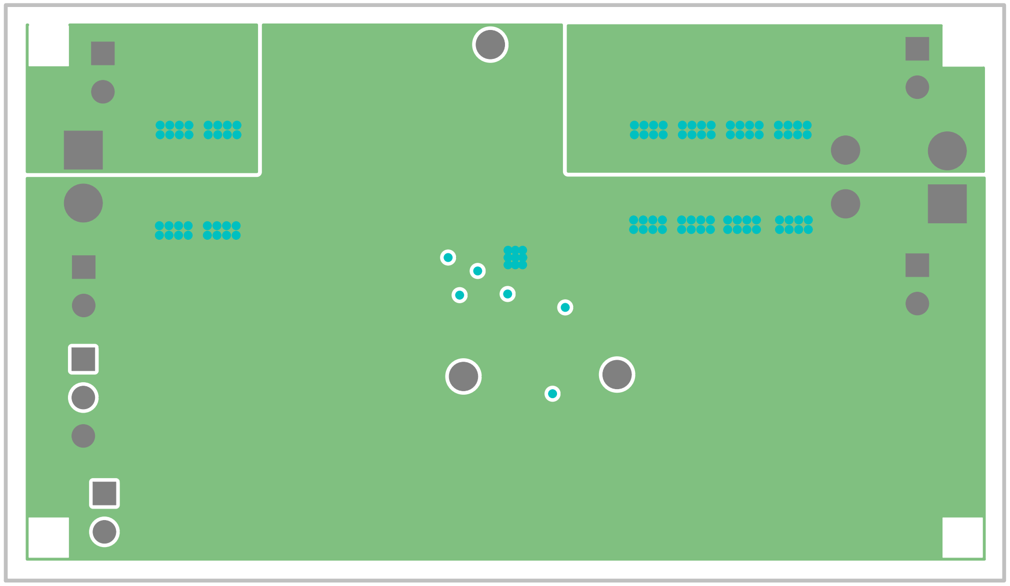


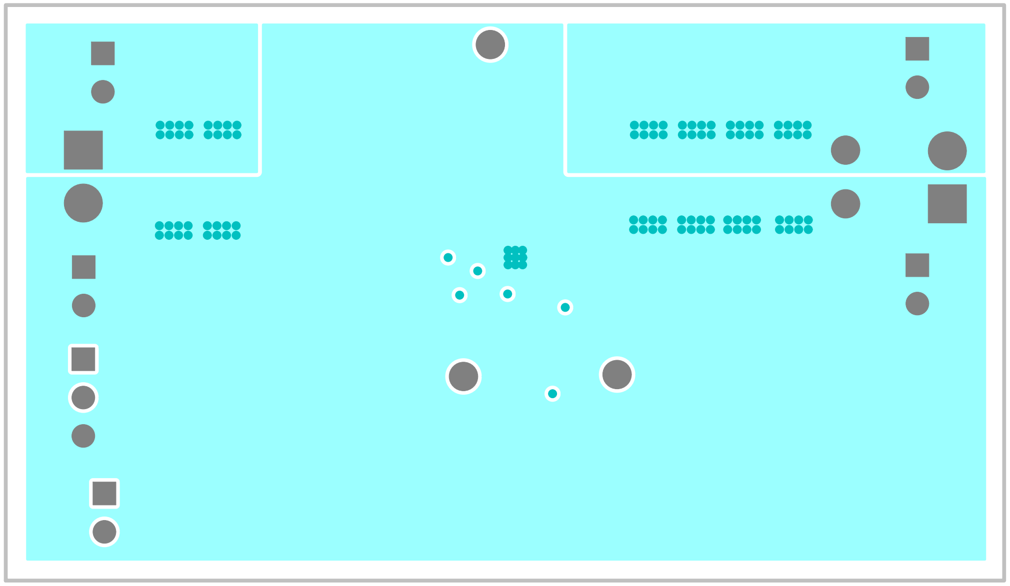
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Dra
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR017	Rev. A	L1												

Date: 2/8/2012
Filename: PWR017A.pcb
Engineer: A. Fagnani
PCB Dsgnr: A. Fagnani
Modified Date: 2/8/2012
Time Stamp: 09:04:



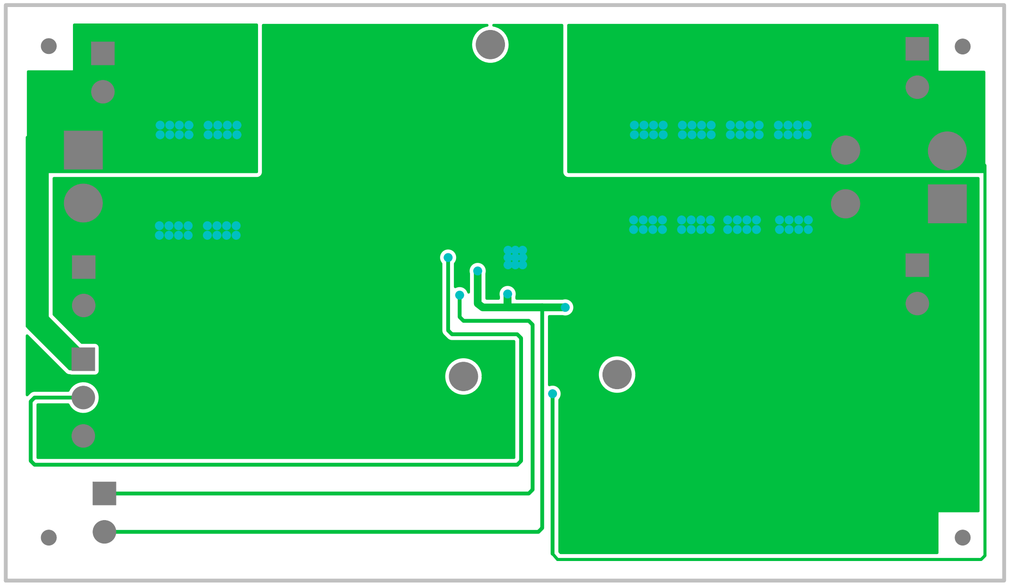
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Dra
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR017	Rev. A		L2											

Date: 2/8/2012	Filename: PWR017A.pcb	Engineer: A. Fagnani	PCB Dsgnr: A. Fagnani	Modified Date: 2/8/2012	Time Stamp: 09:04:



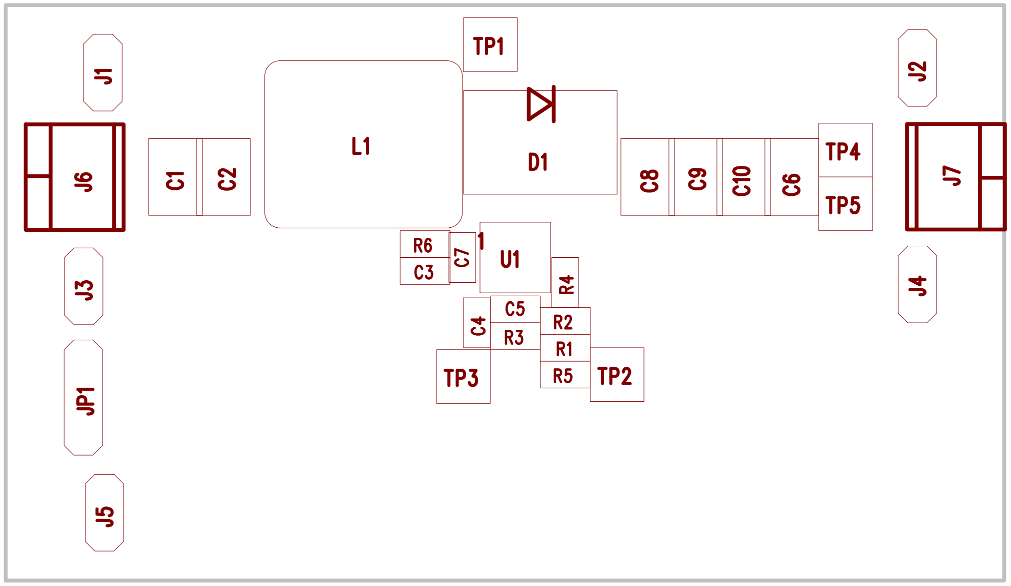
TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Fab Dra
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR017	Rev. A		L3										

Date: 2/8/2012	Filename: PWR017A.pcb	Engineer: A. Fagnani	PCB Dsgnr: A. Fagnani	Modified Date: 2/8/2012	Time Stamp: 09:04:



<table>
<tr><td colspan="2" rowspan="2">TEXAS INSTRUMENTS</td><td colspan="4">Copper Layer Name</td><td colspan="2">Silkscreen</td><td colspan="2">S Mask</td><td colspan="2">P Mask</td><td colspan="2">Assembly</td><td rowspan="2">Fab Dra</td></tr>
<tr><td>Top</td><td colspan="2">Internal</td><td>Bot</td><td>Top</td><td>Bot</td><td>Top</td><td>Bot</td><td>Top</td><td>Bot</td><td>Top</td><td>Bot</td></tr>
<tr><td>Board No. PWR017</td><td>Rev. A</td><td></td><td></td><td></td><td>L4</td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></tr>
</table>

Date: 2/8/2012	Filename: PWR017A.pcb	Engineer: A. Fagnani	PCB Dsgnr: A. Fagnani	Modified Date: 2/8/2012	Time Stamp: 09:04:



TEXAS INSTRUMENTS

Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Dra
Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
L1										TA		

Board No.	Rev.
PWR017	A

Date:	Filename:	Engineer:	PCB Dsgnr:	Modified Date:	Time Stamp:
2/8/2012	PWR017A.pcb	A. Fagnani	A. Fagnani	2/8/2012	09:04:

TEXAS INSTRUMENTS														
Board No. PWR017	Rev. A	Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab D
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
					L4								BA	

Date:	Filename:	Engineer:	PCB Dsgnr:	Modified Date:	Time Stamp:
2/8/2012	PWR017A.pcb	A. Fagnani	A. Fagnani	2/8/2012	09:0

FABRICATION CHART

FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT EXTERNAL	FINISHED COPPER WEIGHT INTERNAL
☐ 0.031	■ LAYER 1	■ LAYER 1	☐ 1 OZ.	☐ 1 OZ.
■ 0.062	☐ LAYER 2	■ LAYER 2	■ 2 OZ.	■ 2 OZ.
☐ 0.093	☐ NONE	☐ NONE	☐ OTHER ____	☐ OTHER ____
☐ 0.125				

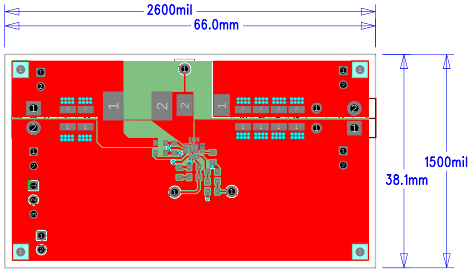
DESIGN	TRACE/GAP SPACING	LAYER COUNT	
☐ SMD	☐ 0.010/0.010	☐ SINGLE SIDED	☐ 2 LAYER
☐ THRU-HOLE	■ 0.008/0.006	■ 4 LAYER	☐ 6 LAYER
■ MIX	☐ 0.006/0.006	☐ 8 LAYER	☐ 10 LAYER
		☐ OTHER ____	

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
2. BASE LAMINATE: PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM COMPOSITION TEMP (Td) OF 320 Deg c.

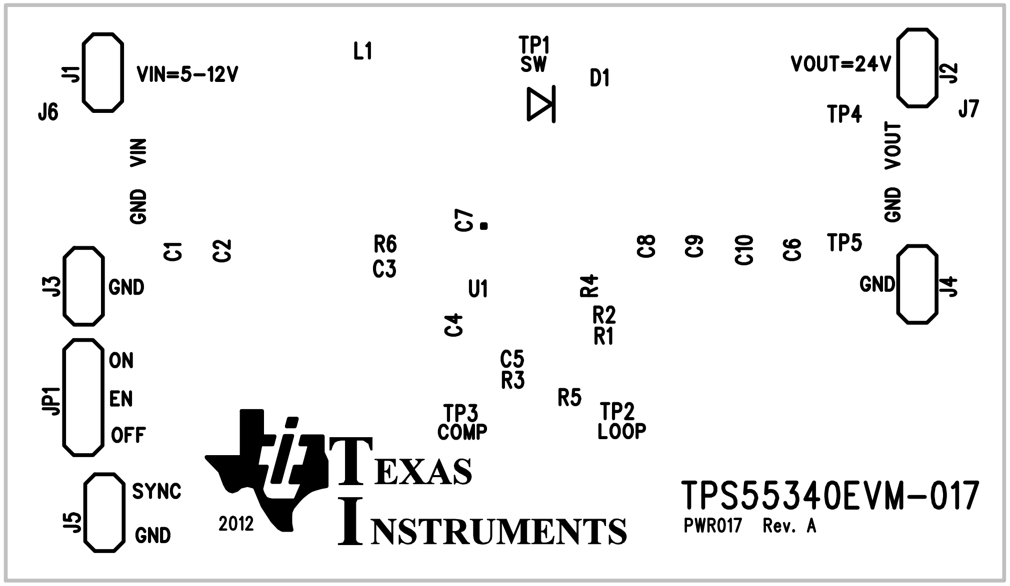
   GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 4 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
4. TOLERANCES: UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.
5. PLATING: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
6. FINISH: PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS

   AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
7. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
8. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
9. WORKMANSHIP: BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
10. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
11. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
12. PANEL BORDER: ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
13. PROCESS CHANGES: NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.



TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR017	Rev. A	L1	L2	L3	L4	S1	S4	M1	M4	P1	P4	TA	BA	FB

Date: 2/8/2012 | Filename: PWR017A.pcb | Engineer: A. Fagnani | PCB Dsgnr: A. Fagnani | Modified Date: 2/8/2012 | Time Stamp: 09:04:55


J1
VIN=5–12V
J6
L1
TP1
SW
D1
VOUT=24V
J2
J7
TP4
VIN
GND
VOUT
GND
C7
R6
C3
C1
C2
C8
C9
C10
C6
TP5
J3
GND
U1
R4
GND
J4
C4
R2
R1
JP1
ON
EN
OFF
C5
R3
R5
TP3
COMP
TP2
LOOP
TEXAS INSTRUMENTS
2012
J5
SYNC
GND
TPS55340EVM–017
PWR017 Rev. A

L1 S1

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